

SPECIFICATIONS:

ELECTRICAL:

RATED CURRENT:	5A
RATED VOLTAGE:	300VDC
WITHSTANDING VOLTAGE:	500VAC (rms) FOR 1 MIN
INSULATION RESISTANCE:	> 1,000 mΩ at 500VDC
CONTACT RESISTANCE:	13mOhms MAX
DIELECTRIC STRENGTH:	1000VAC FOR 1 MIN
OPERATING TEMPERATURE:	-55°C TO +105°C

MATERIALS:

SHELL:	NICKEL PLATED STEEL
BRACKET:	NICKEL PLATED STEEL
INSULATOR:	NYLON 6T, UL 94V-0, BLACK
PROCESS TEMP:	260°C
INSULATOR:	PATONE #322C, COLOR=Pc99
CONTACT:	TIN PLATED PHOSPHOR BRONZE
	MATING AREA (SEE P/N KEY)
	TIN PLATED PCB SOLDER AREA

Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommended to bake at the above temperature and time prior to SMT reflow process.

190-025-163R00Y

CONTACT PLATING (MATING AREA):

1 = GOLD FLASH
2 = 30μ" GOLD

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING

DRAWN:

C. SMITH

DATE:

04/14/2009

SCALE:

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OF

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13

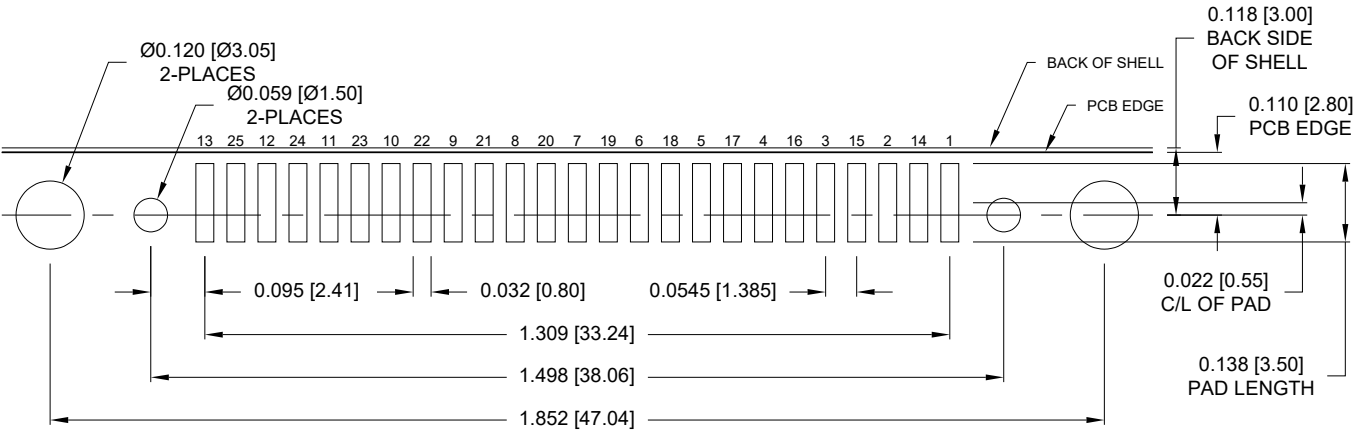
DWG NO.

190-025-163R001

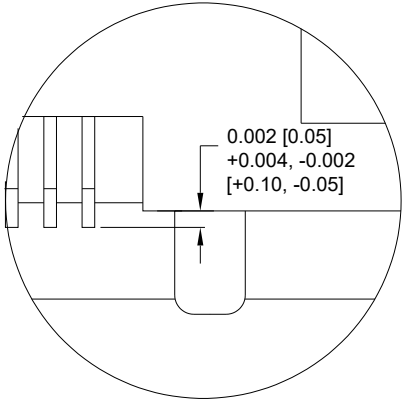


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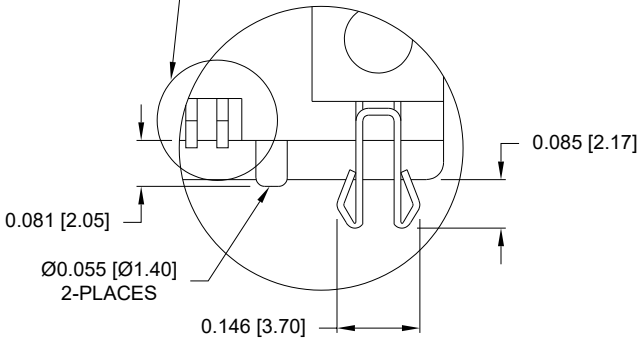


RECOMMENDED PCB LAYOUT

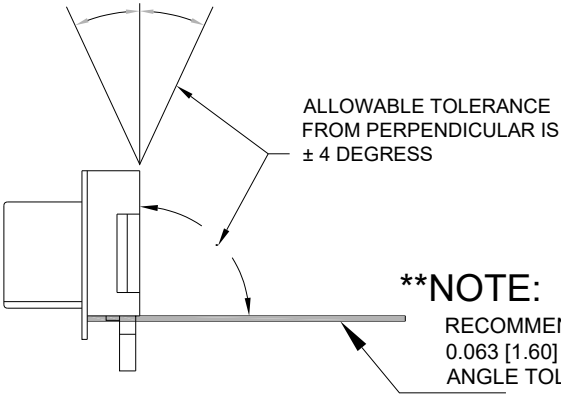


DETAIL "B"
CONTACT COPLANARITY

SEE DETAIL "B"
FOR CONTACT
COPLANARITY



DETAIL "A"



****NOTE:**
RECOMMENDED PCB THICKNESS IS
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN
ANGLE TOLERANCE

RoHS COMPLIANT



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